

Features

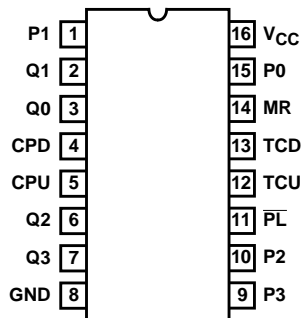
- Synchronous Counting and Asynchronous Loading
- Two Outputs for N-Bit Cascading
- Look-Ahead Carry for High-Speed Counting
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

The 'HC192, 'HC193 and 'HCT193 are asynchronously presettable BCD Decade and Binary Up/Down synchronous counters, respectively.

Pinout

CD54HC192, CD54HC193, CD54HCT193 (CERDIP)
 CD74HC192 (PDIP, SOP, TSSOP)
 CD74HC193 (PDIP, SOIC)
 CD74HCT193 (PDIP)
 TOP VIEW



Presetting the counter to the number on the preset data inputs (P0-P3) is accomplished by a LOW asynchronous parallel load input (\overline{PL}). The counter is incremented on the low-to-high transition of the Clock-Up input (and a high level on the Clock-Down input) and decremented on the low to high transition of the Clock-Down input (and a high level on the Clock-up input). A high level on the MR input overrides any other input to clear the counter to its zero state. The Terminal Count up (carry) goes low half a clock period before the zero count is reached and returns to a high level at the zero count. The Terminal Count Down (borrow) in the count down mode likewise goes low half a clock period before the maximum count (9 in the 192 and 15 in the 193) and returns to high at the maximum count. Cascading is effected by connecting the carry and borrow outputs of a less significant counter to the Clock-Up and Clock-Down inputs, respectively, of the next most significant counter.

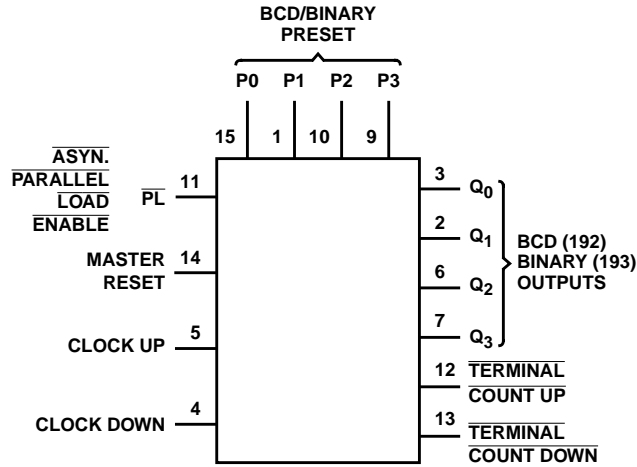
If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it will return to the normal sequence in one count as shown in state diagram.

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC192F3A	-55 to 125	16 Ld CERDIP
CD54HC193F3A	-55 to 125	16 Ld CERDIP
CD54HCT193F3A	-55 to 125	16 Ld CERDIP
CD74HC192E	-55 to 125	16 Ld PDIP
CD74HC192NSR	-55 to 125	16 Ld SOP
CD74HC192PW	-55 to 125	16 Ld TSSOP
CD74HC192PWR	-55 to 125	16 Ld TSSOP
CD74HC192PWT	-55 to 125	16 Ld TSSOP
CD74HC193E	-55 to 125	16 Ld PDIP
CD74HC193M	-55 to 125	16 Ld SOIC
CD74HC193MT	-55 to 125	16 Ld SOIC
CD74HC193M96	-55 to 125	16 Ld SOIC
CD74HCT193E	-55 to 125	16 Ld PDIP

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Functional Diagram



TRUTH TABLE

CLOCK UP	CLOCK DOWN	RESET	PARALLEL LOAD	FUNCTION
↑	H	L	H	Count Up
H	↑	L	H	Count Down
X	X	H	X	Reset
X	X	L	L	Load Preset Inputs

H = High Voltage Level, L = Low Voltage Level, X = Don't Care, ↑ = Transition from Low to High Level

CD54/74HC192, CD54/74HC193, CD54/74HCT193

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 7V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC V_{CC} or Ground Current, I_{CC} or I_{GND}	$\pm 50mA$

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):	
E (PDIP) Package	67°C/W
M (SOIC) Package	73°C/W
NS (SOP) Package	64°C/W
PW (TSSOP) Package	108°C/W
Maximum Junction Temperature	150°C
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range (T_A)	-55°C to 125°C
Supply Voltage Range, V_{CC}	
HC Types2V to 6V
HCT Types	4.5V to 5.5V
DC Input or Output Voltage, V_I , V_O	0V to V_{CC}
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS			25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)	V_{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	6	5.9	-	-	5.9	-	5.9	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	V_{OL}	V_{IH} or V_{IL}	0.02	6	-	-	0.1	-	0.1	-	0.1	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	0	6	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	± 0.1	-	± 1	-	± 1	μA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	μA

CD54/74HC192, CD54/74HC193, CD54/74HCT193

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS			25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} to GND	-	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	-	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} - 2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
P0-P3	0.4
MR	1.45
PL	0.85
CPU, CPD	1.45

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g. 360μA max at 25°C.

CD54/74HC192, CD54/74HC193, CD54/74HCT193

Prerequisite For Switching Specifications

PARAMETER	SYMBOL	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES										
Pulse Width CPU, CPD 192	t _W	2	115	-	-	145	-	175	-	ns
		4.5	23	-	-	29	-	35	-	ns
		6	20	-	-	25	-	30	-	ns
CPU, CPD 193	t _W	2	100	-	-	125	-	150	-	ns
		4.5	20	-	-	25	-	30	-	ns
		6	17	-	-	21	-	26	-	ns
\overline{PL}	t _W	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns
MR	t _W	2	100	-	-	125	-	150	-	ns
		4.5	20	-	-	25	-	30	-	ns
		6	17	-	-	21	-	26	-	ns
Set-up Time Pn to \overline{PL}	t _{SU}	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns
Hold Time Pn to \overline{PL}	t _H	2	0	-	-	0	-	0	-	ns
		4.5	0	-	-	0	-	0	-	ns
		6	0	-	-	0	-	0	-	ns
Hold Time CPD to CPU or CPU to CPD	t _H	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns
Recovery Time \overline{PL} to CPU, CPD	t _{REC}	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns
MR to CPU, CPD	t _{REC}	2	5	-	-	5	-	5	-	ns
		4.5	5	-	-	5	-	5	-	ns
		6	5	-	-	5	-	5	-	ns
Maximum Frequency CPU, CPD 192	f _{MAX}	2	5	-	-	4	-	3	-	MHz
		4.5	22	-	-	18	-	15	-	MHz
		6	24	-	-	21	-	18	-	MHz
CPU, CPD 193	f _{MAX}	2	5	-	-	4	-	3	-	MHz
		4.5	25	-	-	20	-	17	-	MHz
		6	29	-	-	24	-	20	-	MHz
HCT TYPES										
Pulse Width CPU, CPD 192	t _W	2	-	-	-	-	-	-	-	ns
		4.5	23	-	-	29	-	35	-	ns
		6	-	-	-	-	-	-	-	ns
CPU, CPD 193	t _W	2	-	-	-	-	-	-	-	ns
		4.5	23	-	-	29	-	35	-	ns
		6	-	-	-	-	-	-	-	ns

CD54/74HC192, CD54/74HC193, CD54/74HCT193

Prerequisite For Switching Specifications (Continued)

PARAMETER	SYMBOL	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
\overline{PL}	t _W	2	-	-	-	-	-	-	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	-	-	-	-	-	-	-	ns
MR	t _W	2	-	-	-	-	-	-	-	ns
		4.5	20	-	-	25	-	30	-	ns
		6	-	-	-	-	-	-	-	ns
Set-up Time P _n to \overline{PL}	t _{SU}	2	-	-	-	-	-	-	-	ns
		4.5	15	-	-	19	-	22	-	ns
		6	-	-	-	-	-	-	-	ns
Hold Time P _n to \overline{PL}	t _H	2	-	-	-	-	-	-	-	ns
		4.5	0	-	-	0	-	0	-	ns
		6	-	-	-	-	-	-	-	ns
Hold Time CPD to CPU or CPU to CPD	t _H	2	-	-	-	-	-	-	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	-	-	-	-	-	-	-	ns
Recovery Time \overline{PL} to CPU, CPD	t _{REC}	2	-	-	-	-	-	-	-	ns
		4.5	15	-	-	19	-	22	-	ns
		6	-	-	-	-	-	-	-	ns
MR to CPU, CPD	t _{REC}	2	-	-	-	-	-	-	-	ns
		4.5	5	-	-	5	-	5	-	ns
		6	-	-	-	-	-	-	-	ns
Maximum Frequency CPU, CPD 192	f _{MAX}	2	-	-	-	-	-	-	-	MHz
		4.5	22	-	-	18	-	15	-	MHz
		6	-	-	-	-	-	-	-	MHz
CPU, CPD 193	f _{MAX}	2	-	-	-	-	-	-	-	MHz
		4.5	22	-	-	18	-	15	-	MHz
		6	-	-	-	-	-	-	-	MHz

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay CPU to \overline{TCU}	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	125	-	155	-	190	ns
		C _L = 50pF	4.5	-	-	25	-	31	-	38	ns
		C _L = 15pF	5	-	10	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	21	-	26	-	32	ns
CPD to \overline{TCU}	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	125	-	155	-	190	ns
		C _L = 50pF	4.5	-	-	25	-	31	-	38	ns
		C _L = 15pF	5	-	10	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	21	-	26	-	32	ns
CPU to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	220	-	270	-	325	ns
		C _L = 50pF	4.5	-	-	43	-	54	-	65	ns
		C _L = 15pF	5	-	18	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	37	-	46	-	55	ns

CD54/74HC192, CD54/74HC193, CD54/74HCT193

Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
CPD to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	220	-	270	-	325	ns
		C _L = 50pF	4.5	-	-	43	-	54	-	65	ns
		C _L = 15pF	5	-	18	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	37	-	46	-	55	ns
P _L to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	220	-	275	-	330	ns
		C _L = 50pF	4.5	-	-	44	-	55	-	66	ns
		C _L = 15pF	5	-	18	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	37	-	47	-	56	ns
MR to Q _n	t _{PHL}	C _L = 50pF	2	-	-	200	-	250	-	300	ns
		C _L = 50pF	4.5	-	-	40	-	50	-	60	ns
		C _L = 15pF	5	-	17	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	34	-	43	-	51	ns
Transition Time Q, TCU, TCD	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _{IN}	C _L = 50pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	C _L = 15pF	5	-	40	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay CPU to TCU	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	27	-	34	-	41	ns
		C _L = 15pF	5	-	11	-	-	-	-	-	ns
CPU to TCD	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	27	-	34	-	41	ns
		C _L = 15pF	5	-	11	-	-	-	-	-	ns
CPU to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	40	-	50	-	60	ns
		C _L = 15pF	5	-	17	-	-	-	-	-	ns
CPD to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	40	-	50	-	60	ns
		C _L = 15pF	5	-	17	-	-	-	-	-	ns
P _L to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	46	-	58	-	69	ns
		C _L = 15pF	5	-	21	-	-	-	-	-	ns
MR to Q _n	t _{PHL}	C _L = 50pF	4.5	-	-	43	-	54	-	65	ns
		C _L = 15pF	5	-	18	-	-	-	-	-	ns
Transition Time Q, TCU, TCD	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C _{IN}	C _L = 50pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	C _L = 15pF	5	-	50	-	-	-	-	-	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per gate.
- $P_D = V_{CC}^2 f_i + \sum (C_L V_{CC}^2)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

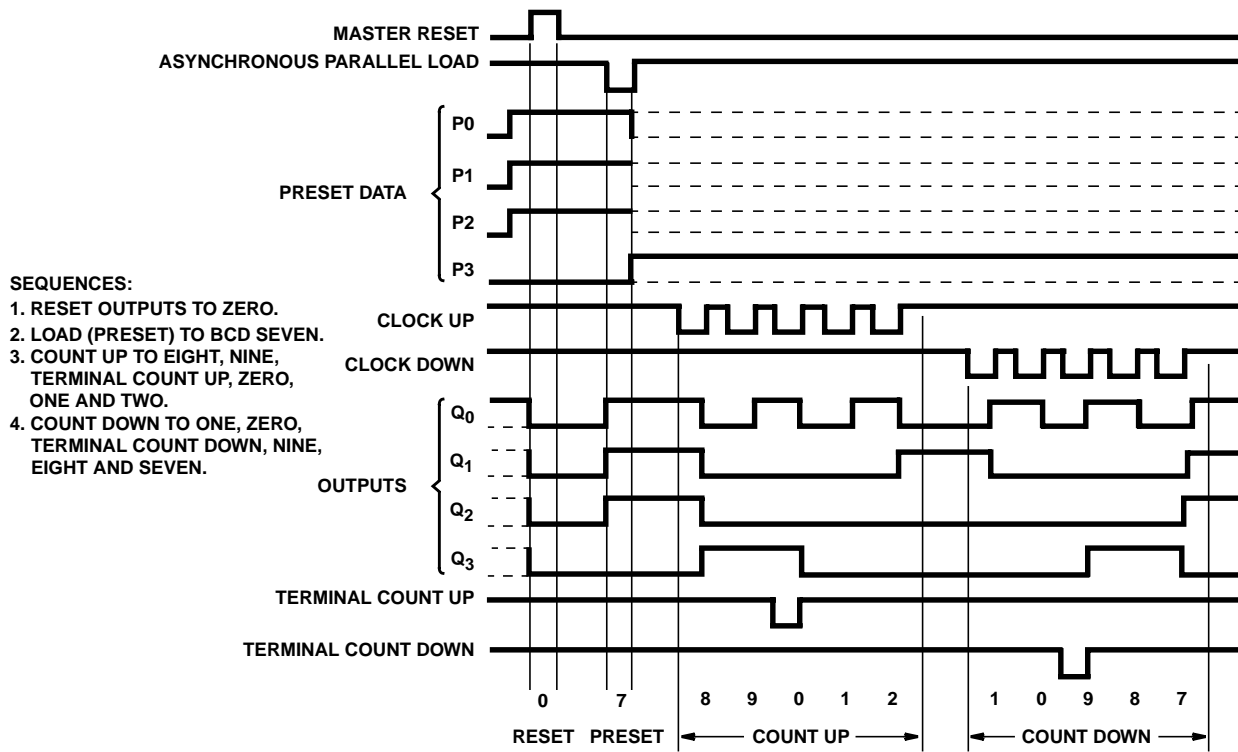


FIGURE 1. 'HC192 SYNCHRONOUS DECADE COUNTERS, TYPICAL RESET, PRESET AND COUNT SEQUENCES

Test Circuits and Waveforms (Continued)

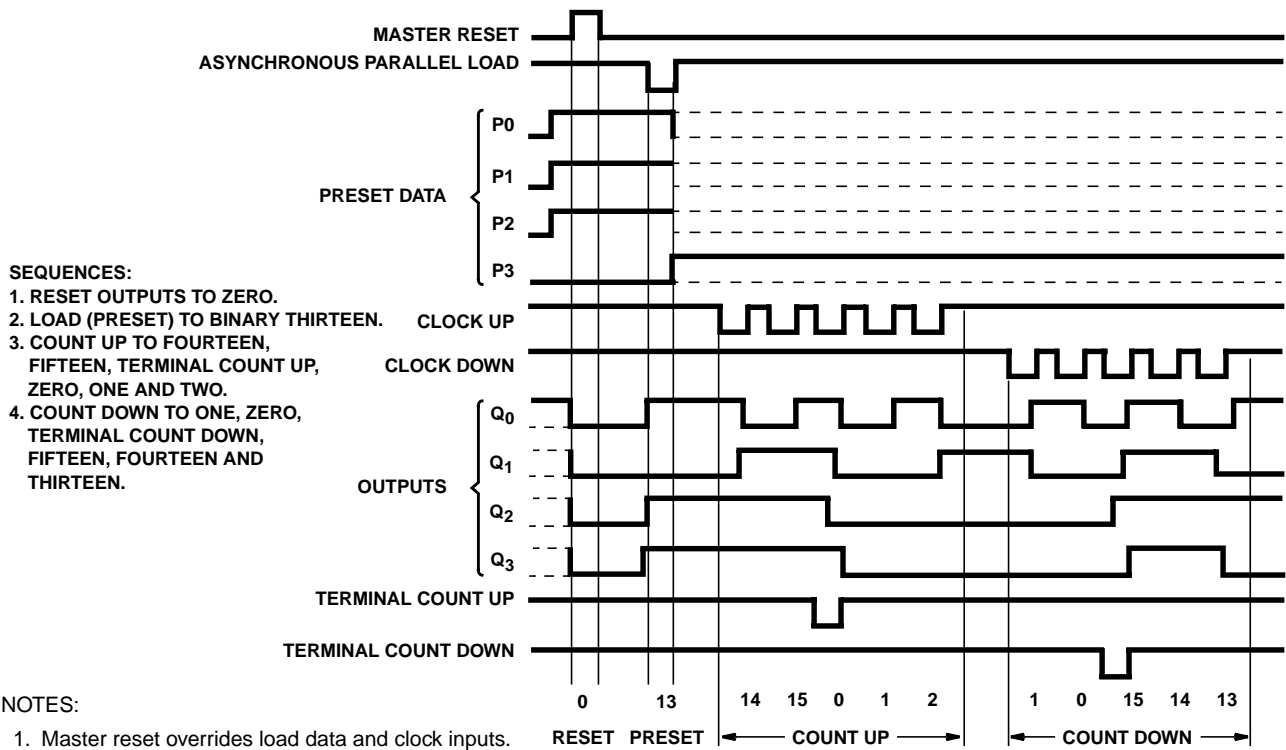


FIGURE 2. 'HC193 SYNCHRONOUS BINARY COUNTERS, TYPICAL RESET, PRESET AND COUNT SEQUENCES

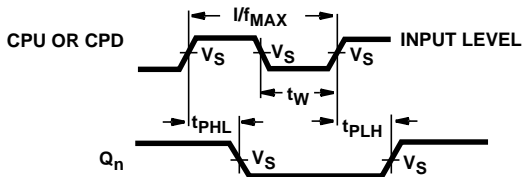


FIGURE 3. CLOCK TO OUTPUT DELAYS AND CLOCK PULSE WIDTH

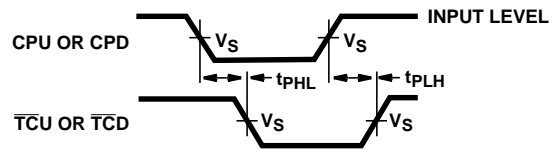


FIGURE 4. CLOCK TO TERMINAL COUNT DELAYS

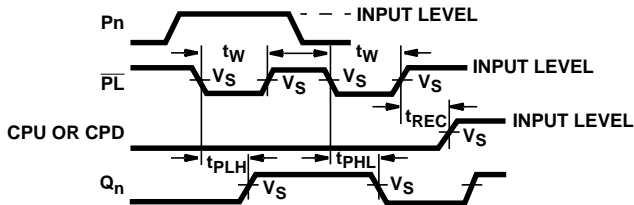


FIGURE 5. PARALLEL LOAD PULSE WIDTH, PARALLEL LOAD TO OUTPUT DELAYS, AND PARALLEL LOAD TO CLOCK RECOVERY TIME

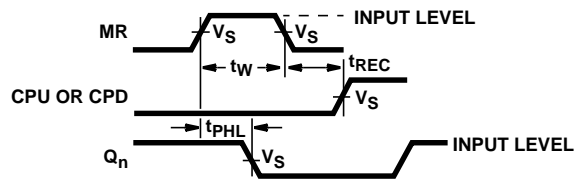


FIGURE 6. MASTER RESET PULSE WIDTH, MASTER RESET TO OUTPUT DELAY AND MASTER RESET TO CLOCK RECOVERY TIME

Test Circuits and Waveforms (Continued)

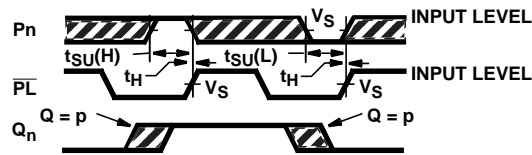


FIGURE 7. SET-UP AND HOLD TIMES DATA TO PARALLEL LOAD (PL)

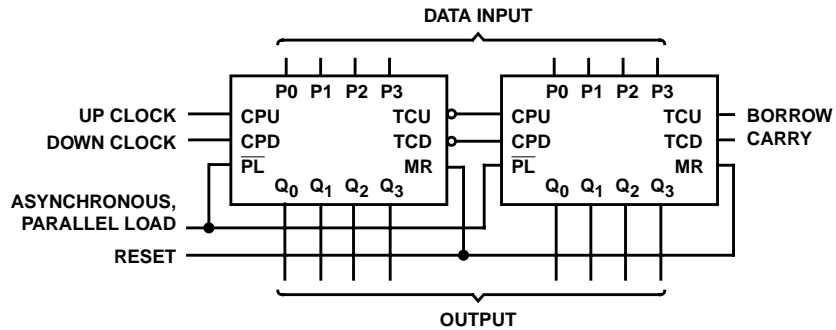
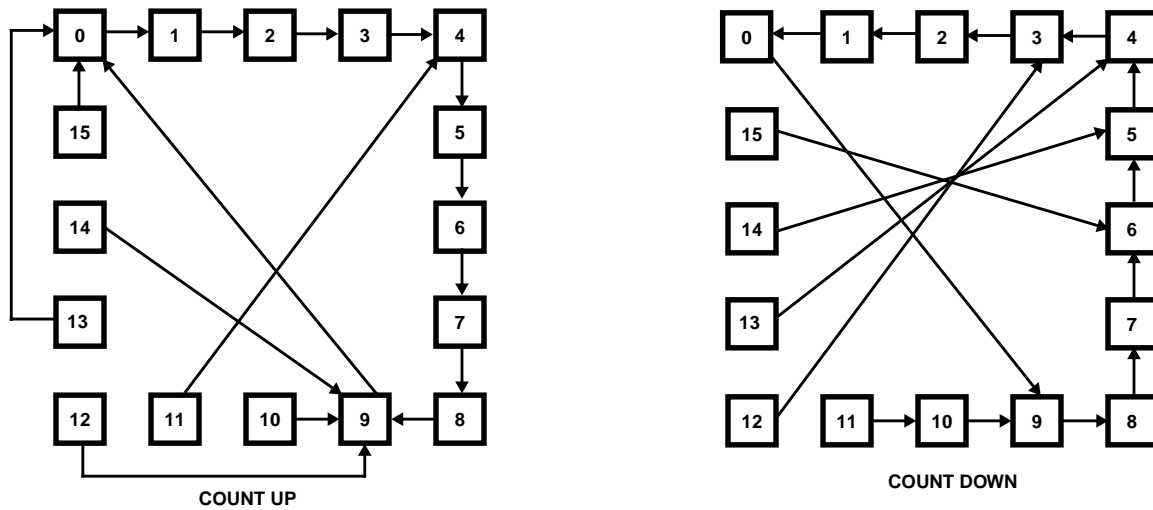


FIGURE 8. CASCADED UP/DOWN COUNTER WITH PARALLEL LOAD



NOTE: Illegal states in BCD counters corrected in one count.

NOTE: Illegal states in BCD counters corrected in one or two counts.

FIGURE 9. 'HC192, 'HCT193 STATE DIAGRAMS

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-8780801EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-9084801MEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
9084801MEAS2035	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
CD54HC192F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HC193F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HCT193F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD74HC192E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC192EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC192NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC192PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC193EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC193M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC193M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC193MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT193E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT193EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD54HC192, CD54HC193, CD54HCT193, CD74HC192, CD74HC193, CD74HCT193 :

- Catalog: [CD74HC192](#), [CD74HC193](#), [CD74HCT193](#)
- Military: [CD54HC192](#), [CD54HC193](#), [CD54HCT193](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC192NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC192PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC192PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC193M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC192NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC192PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC192PWT	TSSOP	PW	16	250	367.0	367.0	35.0
CD74HC193M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

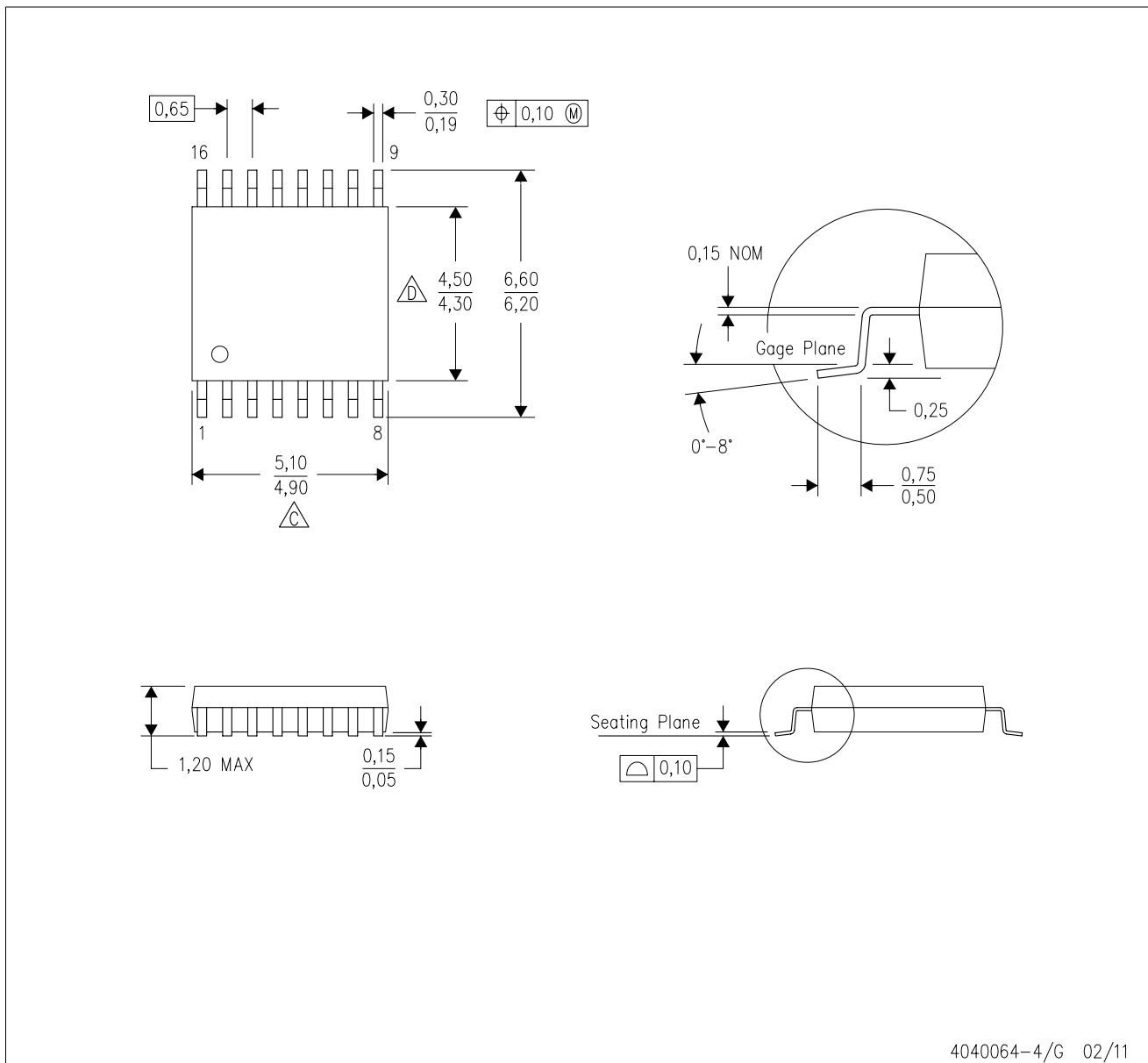
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

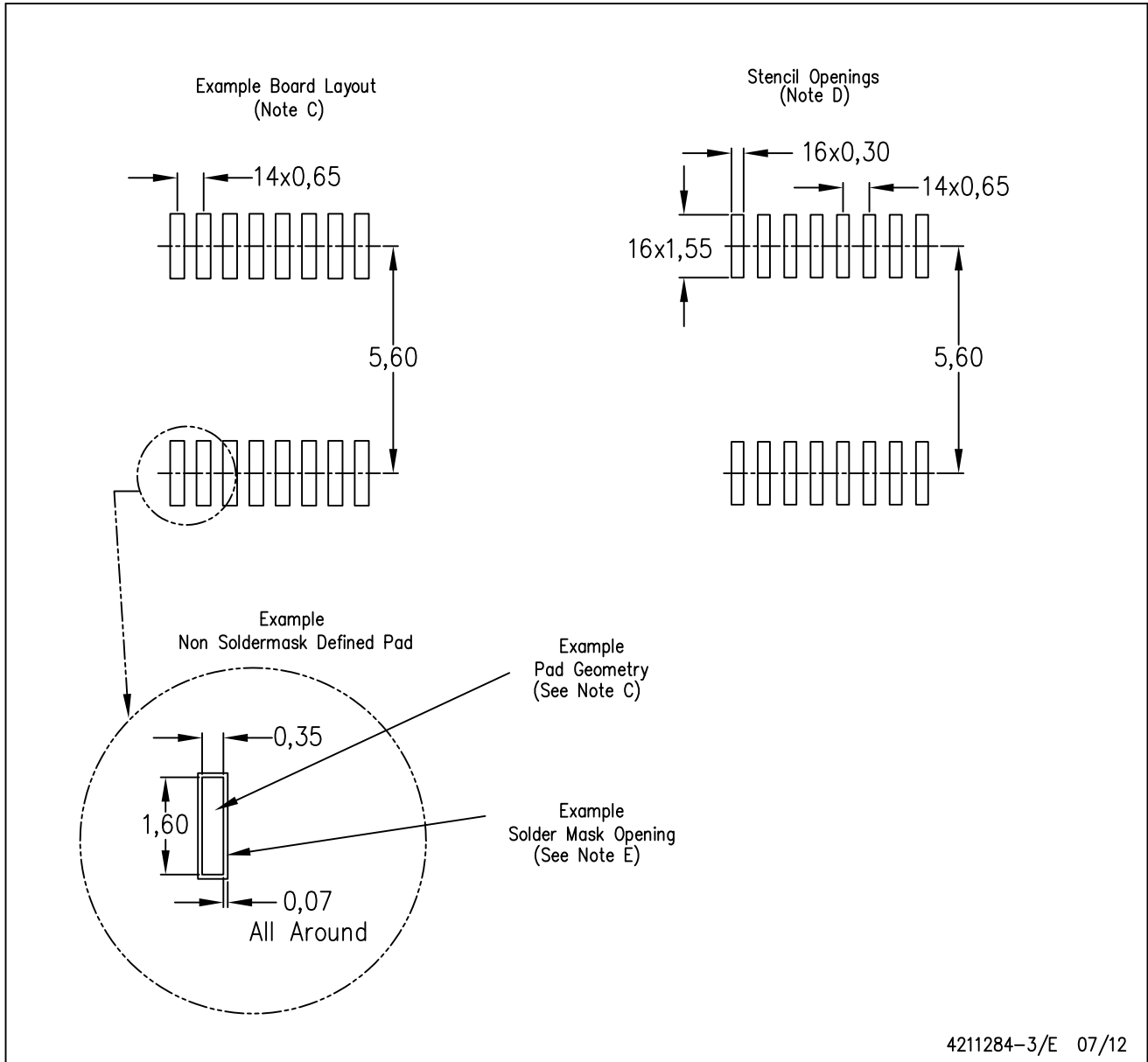


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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